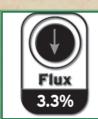




Wire Solder

To manufacture low residue/fine diameter wire solders, Qualitek utilizes state-of-the-art wire extrusion and wire drawing machines. Many of our formulations use the latest in no-clean/low residue technology found in our solder pastes and solder fluxes. We also developed our flux core manufacturing process to eliminate flux voids and irregular wire. Formulations available for: No-Clean, Water-Soluble, Rosin Mildly Activated, Super Activated Resin and Rosin Activated. Solid wire is also available. Qualitek wire solders meet or exceed J-STD-006.

Standard Flux Core Percent







Delta Tip Tinner

Tip Tinner is a mixture of solder powder and thermally stable, oxide-reducing compounds. Tip Tinner provides better cleaning and re-tinning of highly oxidized soldering iron tips than wet sponge or rosin-cored wire. Very effective for cleaning and retinning soldering iron tips. Available in several alloys including Sn63/Pb37 and Sn62/Pb36/Ag2. Lead free alloys are also available.

When ordering, specify solder alloy, wire diameter, flux-core type and percent, including spool size.

Wire Solder

Wire Formula	Residue Removal By	Flux Class per J-STD-004
NC600 No-Clean	Not required. If desired,	REL0
	Solvent/Semi Aqueous	
NC601 No-Clean	Not required	ORL0
	If desired, hot water	
NC609 No-Clean Colophony free	Not required	REL0
	If desired, hot water	
WS700 Water-Soluble	Hot DI water	ORH1
RMA200 Rosin Mildly Activated	Solvent/Semi-Aqueous	ROL1
RA 300 Activated Rosin	Solvent/Semi-Aqueous	ROM1
SRA500 Rosin Super Activated	Solvent/Semi-Aqueous	ROM1
Solid Wire No Flux Core	NA	NA

Standard Packaging Spools

91	andard Fackaging Sp	,001	3		
•	1/2 lb.	•	1 kilogram	•	10 lb.
•	1 lb.	•	5 lb.	•	20 lb.

Standard Wire Diameters

Diameter (inch)	0.125	0.092	0.062	0.050	0.040	0.032	0.025	0.020	0.015	0.010
Diameter (mm)	3.18	2.33	1.57	1.27	1.01	0.81	0.63	0.50	0.38	0.25
Std. Wire Gauge	11	13	16	18	19	21	23	25	28	31

Q-Bar

Qualitek Q-Bar is made from grade A Virgin metals. Quality standards for all Q-Bar exceed J-STD 006 and ASTM B-32. Q-Bar is available in one Kilogram bars.

Q-Bar Chips

Q-Bar chips are ideal for pot start-up, and small selective soldering pots. They can easily be loaded into melting pots. The dimensions of the chips are one half inch by one inch. Quality standards for Q-Bar Chips are the same as Q-Bar.

Equalizer Bar

Qualitek Equalizer bar is an extruded bar with the same quality standards as Q-Bar. It is designed for maintaining the solder level in automated wave soldering machines. It's available in 5 kilograms bar or 11 pounds.

Super Top

Super Top is a solder additive designed for wave solder pots or dip-tinning pots. Adding Super Top to a melting pot will dramatically decrease dross formation and reduce solder loss. Added quantity of Super Top will vary depending on the quantity of molten solder. Available for leaded and lead free pots.

Super Deox #1

Dross Eliminator

Specifically formulated to convert the oxides of solder (known as dross) into good solder. Super Deox #1 is a stable, low fuming, high melting compound with no flash or fire points. Use of Super Deox can reclaim over 80% of dross into usable solder. This can substantially reduce solder cost. Also available for Lead Free pots.

Solder Check Up Program

Qualitek offers a convenient and accurate method for the rapid analysis of your pot solder. Periodic analysis is needed to maintain solder pot integrity. Solder pot analysis is generally recommended every 30 days. This is necessary to track contaminants that may cause a variety of quality and solderability issues. The test will consist of a 1/2lbs sample sent to one of our worldwide locations. We will have the results within one day. To best suit your needs, there are three solder check-up programs (A, B and C) from which to choose.

Program A - Economical

Includes: Tin, Antimony, Gold and Copper.

Program B - Standard

Includes: Tin, Antimony, Gold, Copper, Cadmium, Indium, Zinc, Aluminum, Iron, Arsenic, Silver, Nickel and Bismuth.

Program C - Complete

Includes: Tin, Antimony, Gold, Copper, Cadmium, Indium, Zinc, Aluminum, Iron, Bismuth, Silver, Nickel, Sulfur, Phosphorus and Arsenic.

Common Alloys

Alloy Composition	Melting Ran Fahrenheit	ge Celsius
Tin/Lead Sn63/Pb37 Sn60/Pb40 Sn50/Pb50 Sn45/Pb55 Sn40/Pb60 Sn20/Pb80 Sn10/Pb90	361E 361-374 361-420 361-440 361-460 361-536 514-576	183E 183-190 183-214 183-225 183-238 183-280 268-302
Other Alloys Sn62/Pb36/Ag2 Sn48/In52 Sn43/Pb43/Bi14 Sn10/Pb88/Ag2 E-Eutectic	354-372 244E 291-325 514-570 Refer to lead free brochure for addit	179-189 118E 144-163 268-299 ional alloys.

Maximum Allowable Impurities

	Q-BAR	J-STD-006	ASTM B-32
Antimony	0.050	0.200	0.120
Copper	0.010	0.080	0.080
Silver	0.010	0.050	0.015
Bismuth	0.050	0.100	0.250
Iron	0.010	0.020	0.020
Arsenic	0.010	0.030	0.030
Zinc	0.001	0.003	0.005
Aluminum	0.001	0.005	0.005
Cadmium	0.001	0.002	0.001
Nickel	0.005	0.010	N/A
Gold	0.002	0.050	N/A
Indium	0.050	0.100	N/A

Solder Recycling Program

Qualitek solder recycling program provides customers with a convenient method to dispose of solder dross, pot dumpings, unused solder/solder paste and solder paste scrap. Customers receive maximum return and an additional 5% credit over the settlement value when credit is applied towards the purchase of soldering products from Qualitek.

To participate in this program, simply call Qualitek's customer service. We will supply you with the proper information on shipping and packing of recyclable solder and the suitable containers.

